PCN Number:	20160524	20160524003		PCN Date		5/27/2016	
	for DRV110		<u> </u>			3,2,,2010	
Customer Contact		er			Qua	ity Services	
Change Type:		<u></u>		ор	4.00	,	
Assembly Site		Design		Wafer	Rum	n Site	
Assembly Proce	ess	Data Shee	t -		fer Bump Site fer Bump Material		
Assembly Materials		Part numb		_	afer Bump Process		
	Mechanical Specification				Wafer Fab Site		
Packing/Shipping/Labeling		Test Site Test Proce	SS		afer Fab Materials		
					Wafer Fab Process		
Notification Details							
Description of Change:							
Texas Instruments	ncorporated is	announcing an	information only r	notificatio	n.		
The product datasheet(s) is being updated as summarized below. The following change history provides further details.							
TEXAS INSTRUMENT	TEXAS DRV110						
INSTRUMENT			SLVSBA8	C - MARCH 201	12-REVIS	ED APRIL 2016	
Changes from Revision B (July 2015) to Revision C							
 Changed one test condition (R_{OSC} = 50 kΩ to 160 kΩ) and the maximum value for the Externally set PWM clock frequency (60 to 25) in the <i>Electrical Characteristics</i> table Changed the <i>PWM Clock Frequency Setting</i> graph. 							
The datasheet numl	er will be chai	naina.					
Device Family	ver vviii be endi		Change From:			ge To:	
DRV110		SLVSBA81				BA8C	
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/DRV110 Reason for Change:							
To more accurately	reflect device of	characteristics.					
Anticipated impac			ality or Reliabili	ty (posi	tive /	negative):	
No anticipated impa to the actual device	ct. This is a sp						
Changes to product identification resulting from this PCN:							
None.							
None. Product Affected:							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com